



Radio and Wireless Week



18–21 January 2026

Loews Hollywood Hotel – Los Angeles, CA, USA



The 2026 IEEE Radio and Wireless Week will be held during the week of 18–21 at the Loews Hollywood Hotel – Los Angeles, CA, USA. The IEEE Radio and Wireless Symposium (RWS), the IEEE Topical Meeting on Silicon Monolithic Integrated Circuits (SiRF), and the IEEE Topical conferences held in parallel provide more focused sessions in the areas of RF Power Amplifiers (PAWR), Wireless Sensors and Sensor Networks (WiSNet), and Space Hardware and Radio (SHaRC). The week is accompanied with Special Sessions, Short Courses, and Workshops.



IEEE Radio and Wireless Symposium (RWS)

The Radio and Wireless Symposium is the heart of the IEEE Radio and Wireless Week. The conference provides the latest results in high-speed and broadband wireless technologies for emerging communication system and wireless technologies. It includes all frequency bands up to mm-wave and THz with its individual technologies and applications including passive components, packaging, and novel engineered materials for different applications.



IEEE Topical Conference on RF/Microwave Power Amplifiers for Radio and Wireless Applications (PAWR)

Power amplifiers for radio and wireless applications (PAWR) are often the most critical component of RF/microwave communications systems and consequently the focus of intense research to achieve increased linearity and power efficiency. New forms of power amplification are being developed to meet the needs for wireless communication, instrumentation, and sensing satisfying the world's demand for sustainable interconnectivity. PAWR 2026 will feature tracks on RF/microwave Power Amplifiers.



IEEE Topical Conference on Wireless Sensors and Sensor Networks (WiSNet)

Wireless sensors and wireless sensor networks (WiSNet) are crucial components for manufacturing, structural health, security monitoring, environmental monitoring, smart agriculture, transportation, commercial applications, localization, tracking systems and other important and emerging applications. WiSNet is intended to stimulate discussion and foster innovation on these components and applications.



IEEE Topical Meeting on Silicon Monolithic Integrated Circuits in RF Systems

RF CMOS and Si/SiGe BiCMOS technologies are well established in commercial and defense applications. SiRF provides a platform between IC designers and researchers promoting non-standard technologies, exploiting the maturity of Silicon processes, but addressing the challenges of tomorrow. The three days of SiRF will chronicle recent advances in our dynamic field, and provide the platform for developing new ideas, and candid exchange, facilitated by SiRF's single-session format. A line-up of reputed invited speakers will stimulate our discussions, with an emphasis on emerging technologies.



IEEE Space Hardware and Radio Conference (SHaRC)

SHaRC addresses new concepts, novel implementations, as well as emerging applications for space-based electronic systems for communications, earth observation, and other novel disruptive services. To meet recent needs, there has been a renaissance of interest and investment in space- and suborbital-based systems especially for high-data-rate communications networks. These new global satellite networks are disruptive, rely on new system and subsystem design paradigms, and are an enabler for many novel applications. The conference provides a forum for discussions on this new frontier.

Paper submission instructions can be found at www.radiowirelessweek.org. Submissions should be formatted according to the submission review template available on the RWW website. Authors should indicate preference for oral or poster presentation. All submissions must be received by **23 July 2025**. All accepted papers will be published in a digest and presented papers will be included in the IEEE Xplore® Digital Library. Submissions will be evaluated based on novelty, significance of the work, technical content, interest to the audience, and quality of writing.



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Call For Papers

The 2026 IEEE Radio and Wireless Symposium (RWS 2026) will be held during the week of 18–21 January 2026 at the Loews Hollywood Hotel – Los Angeles, CA, USA. RWS 2026 and the IEEE Topical Meeting on Silicon Monolithic Integrated Circuits (SiRF 2026) are co-located and will continue to hold joint sessions. Topical conferences held in parallel provide more focused sessions in the areas of RF Power Amplifiers (PAWR), Wireless Sensors and Sensor Networks (WiSNet), and Space Hardware and Radio (SHaRC). The RWW Demonstration Track provides an interactive forum for hands-on demonstration of the latest wireless experiments and innovations. There are also Special Sessions, Short Courses, and Workshops. RWS Papers featuring innovative work are solicited in (but not limited to) the following areas:

1. High-speed and Broadband Wireless Technologies

- Broadband Fixed Wireless and Last-Mile Access
- Optical Networks Systems and Microwave Photonics
- M2M, V2V & V2x Technologies & Applications

2. Emerging Wireless Technologies & Novel Engineered Materials / Processes

- Green, Sustainable Wireless Technologies & Networks
- Wireless Power Transfer
- Quantum Technologies
- Additive 3D manufacturing & Novel Engineered Materials

3. Wireless System Architecture and Propagation Channel Modeling

- Distributed & Ad-Hoc Network Architectures and Systems
- Wireless Mesh and Local/Personal/Body Area Networks

4. Wireless Digital Signal Processing and Artificial Intelligence

- Digital/Analog Adaptive/Collaborative Signal Processing
- Dynamic Spectrum Sharing, Coexistence, Interoperability
- Artificial Intelligence & Machine Learning in Radio and Wireless

5. Applications to Bio-Medical, Environmental, and Internet of Things

- Miniaturization and Integration of Wireless Technologies
- Biological Material Characterization
- Wireless Positioning Technologies & Remote Sensing

6. Antenna Technologies, MIMO and Multi-Antenna Communications

- Multi-Beam Smart Antennas
- Miniaturized, Multi-frequency and Broadband Antennas
- Passive and Active Antennas from RF to THz Frequencies
- Wireless Platform Integrated Antennas

7. Passive Components & Packaging

- 3D-Packaging, Interconnects, and Applications
- Discrete, Embedded and Distributed Passive Components, Filters Couplers and Signal Separation Devices

8. MM-Wave to THz Systems & Applications

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IEEE Topical Conference on RF/Microwave Power Amplifiers for Radio and Wireless Applications

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- IEEE Radio and Wireless Symposium (RWS)
- IEEE Topical Meeting on Silicon Monolithic Integrated Circuits in RF Systems (SiRF)
- IEEE Topical Conference on Wireless Sensors and Sensor Networks (WiSNet)
- IEEE Space Hardware and Radio Conference (SHaRC)
- Workshops, Special Sessions, Short Courses

Each of these events will be organized separately, with their own call for papers found at www.radiowirelessweek.org.

Power amplifiers for radio and wireless applications (PAWR) are often the most critical component of RF/microwave communications systems and consequently the focus of intense research to achieve increased linearity and power efficiency. New forms of power amplification are being developed to meet the needs for wireless communication, instrumentation, and sensing satisfying the world's demand for sustainable interconnectivity. PAWR 2026 will feature tracks on RF/microwave Power Amplifiers. Papers featuring innovative work are solicited in (but not limited to) the following areas of RF/microwave power amplifier technology:

- High Power/Wideband Active Devices
- Power Amplifiers for Mobile, Avionics and Space
- Modeling and Characterization
- Advanced Circuit Design and Topologies
- Green Power Amplifier Technology
- Integration Technology
- Packaging and Reliability
- Linearization and Efficiency Enhancement Techniques
- Applications, Novel Architectures and System Analysis

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Wireless sensors and wireless sensor networks (WiSNet) are crucial components for manufacturing, structural health, security monitoring, environmental monitoring, smart agriculture, transportation, commercial applications, localization, tracking systems and other important and emerging applications. WiSNet is intended to stimulate discussion and foster innovation on these components and applications.

Papers featuring innovative work are solicited in (but not limited to) the following areas:

- Wireless Sensors for Communication, Radar, Positioning and Imaging Applications
- Wireless Sensors for Localization and Tracking
- Wireless Integrated Sensors, Front-Ends and Building Blocks
- Wireless Sensors for Harsh Environments, Environmental, Health, Home and Commercial Applications
- Wireless Sensors Networks, Smart Sensor Systems, and Autonomous Networking
- RFID Sensors and Sensor Tags
- Sensor Networks for Sensor Network Topologies and Sensor Network Communication Architecture
- Coexistence, Synchronization and Scheduling in Hybrid and Social Networks
- Cryptography, Security, Privacy Issues in Ad-Hoc, Sensor and Mesh Networks
- Six-Port and Multi-Port Technology
- Internet of Things Hardware, Protocols and Applications
- Wireless Sensors Applications in Wearable Computing and Body Area Nets
- QoS Aware Design: Energy Optimization and Deployment Techniques, Large, Dense and Dynamic Network Topologies

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Call For Papers

IEEE Topical Meetings on Silicon Monolithic Integrated Circuits in RF Systems have been at the forefront of moving Silicon technologies into microwave, millimeter-wave and THz applications – a development now widely accepted, and of great importance. RF CMOS and Si/SiGe BiCMOS technologies are well established in commercial and defense applications. SiRF 2026 will mark the 26th topical meeting on SiRF, with a renewed emphasis on promoting a dialogue between IC designers and researchers promoting non-standard technologies, exploiting the maturity of Silicon processes, but addressing the challenges of tomorrow. The three days of SiRF 2026 will chronicle recent advances in our dynamic field, and provide the platform for developing new ideas, and candid exchange, facilitated by SiRF's single-session format. As in past years, a line-up of reputed invited speakers will stimulate our discussions, with an emphasis on emerging technologies. For more details, visit: www.radiowirelessweek.org/sirf. SiRF 2026 solicits papers in the following focus areas:

1. RF, Millimeter-Wave, and THz Integrated Circuit Front Ends

- RF/mm-Wave/THz Integrated Circuits, Sub-Systems, and Transceivers
- Integrated Circuits for Phased Array, MIMO, and B5G/6G Systems
- Reconfigurable Front Ends, Multi-Band/Ultra-Wideband Circuits and Systems
- AI-Driven and AI-Enabled RF/mm-Wave Circuits and Emerging Applications

2. Wireline/Optical Communication Circuits and SiPho Integrated Circuits

- Broadband Wireline Transmitters, Receivers, and Transceivers
- High-Speed/Broadband Front Ends (TIA, Driver)
- Oscillators, PLLs, Synthesizers, and Signal Generators
- Advanced Techniques for Clock and Data Recovery (CDR)
- Electronic-Photonic Integrated Circuits and Systems

3. High-Speed Data Converters and Mixed-Signal Integrated Circuits

- Nyquist Rate and Oversampling A/D and D/A Converters
- Time-to-Digital and Analog-to-Information Converters
- Digitally-Assisted Analog Integrated Circuits and Calibration Techniques
- Other Advanced Analog/Mixed-Signal Integrated Circuits

4. Device Technologies, Advanced Packaging, and Heterogeneous Integration

- Advanced bulk CMOS, SOI CMOS, FinFET, and SiGe BiCMOS Process Technology and Device Modeling
- Heterogeneous Integration, System-on-Chip, and System-in-Package
- Through-Silicon Vias, RF MEMs, and Micromachining
- Circuit-Package Interaction and Co-Simulation
- Integrated Antennas, Antenna-in-Package, and Metasurfaces
- Advanced Measurement and De-Embedding Techniques

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The IEEE Space Hardware and Radio Conference (IEEE SHaRC) addresses new concepts, novel implementations, as well as emerging applications for space-based electronic systems for communications, earth observation, and other novel disruptive services. To meet recent needs, there has been a renaissance of interest and investment in space- and suborbital-based systems especially for high-data-rate communications networks. These new global satellite networks are disruptive, rely on new system and subsystem design paradigms, and are an enabler for many novel applications. The IEEE Space Hardware and Radio Conference provides a forum for discussions on this new frontier.

Papers featuring innovative work are solicited in (but not limited to) the following areas of the space hardware and systems:

- Manufacture & Deployment of LEO Satellite Constellations & Formations
- Lower-Cost Alternatives
- Unmanned Air Systems
- Terrestrial Systems & Ground Stations
- CubeSat Hardware and Systems
- Satellite and Balloon Concepts
- Small and Micro-Satellite Design
- Orbital Configurations & Operations
- Radiation Effects
- Phased Arrays
- High Data Rate Links
- Geolocation
- Earth Observation
- Frequency Spectrum Allocations
- International Regulations & Standards
- SIGHT Applications of the IoS

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